

Flash High-Energy Density Physics Co-Design Center

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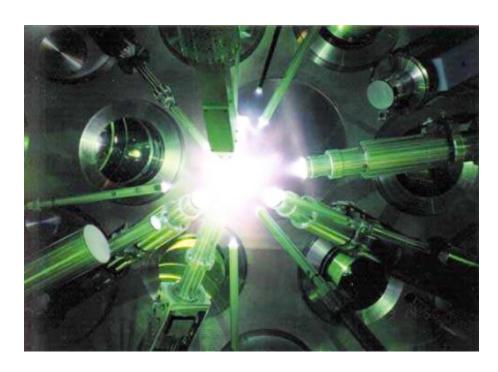






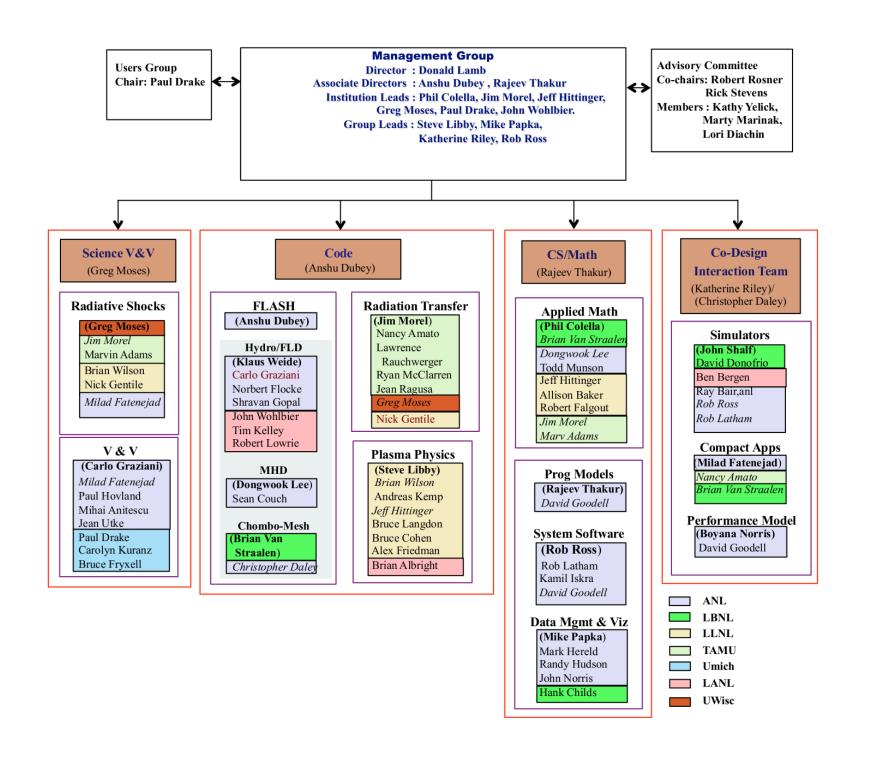


Flash HEDP Co-Design Center Goals



- Enable modeling and simulation of HEDP experiments on exascale computers
 - Allow scientists to address physical regimes and phenomena currently infeasible in the laboratory

- □ Through a rigorously defined co-design structure and process, the Center will apply domain research to identify and tune interdependencies among the hardware, applied mathematics, and computer science, and the application
- □ Incorporate insights from co-design into FLASH to ensure that it is a highly capable exascale code for the academic HEDP community



HPC System Timeline

Concept phase:
Blue Sky design
discussion, R&D,
technology assessment

Design phase: Packaging, chip layout, detailed design Implementation /
Bring-up phase:
Integrate, test, revise,
test at scale

Concept system software Simulations for evaluation

System software, Simulations for V&V, Compilers and Libraries



Co-Design at hardware level



Some Co-Design possible at hardware level, more at system software level

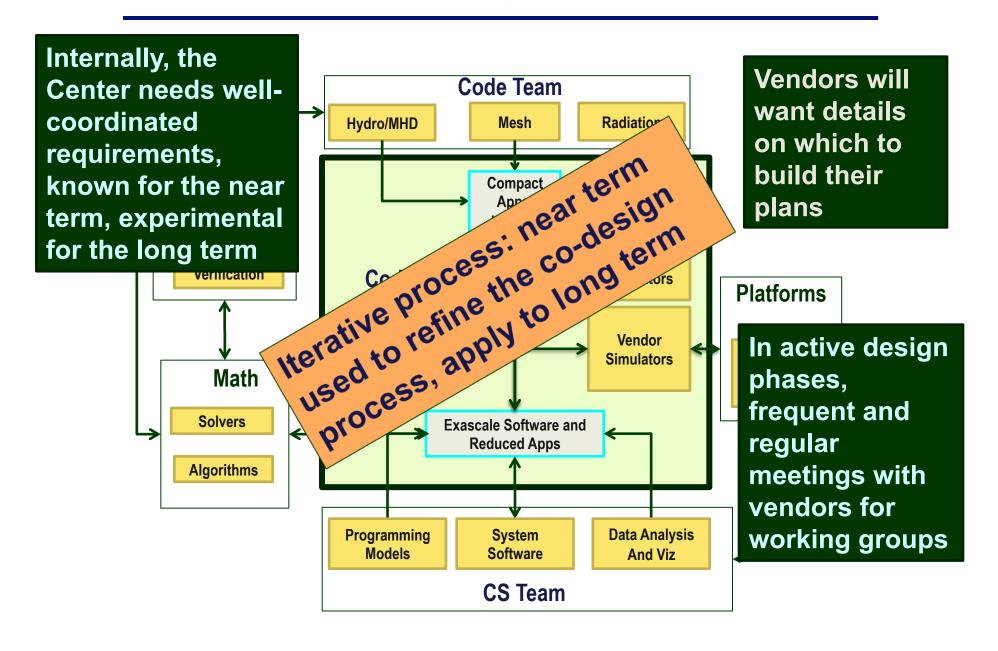


Only useful in diagnostics

Year 1	Year 2	Year 3	Year 4

Window of opportunity for Hardware Changes Closes here...

Flash Co-design Interaction



Integration

Applications/Applied Math Models and Algorithms, Infrastructure Next level workload includes programming Kernels interact directly with hardware **Programming Models:** application with runtime environment have representative Data structures, macro/micro Parallelism access patterns workload for whole sections of the interactio<mark>n</mark> System Software: Operating System, I/O Compact apps Runtime environment Hardware: models Cores, accelerators, memory Communication networks

Repository of Representative Workload

Designated group for managing representative workload in the Co-Design Interaction Team

- Identify code components in the critical path
 - Infrastructure: meta-data and load balancing
 - Physics : memory intensive vs. computation intensive
- Identify code components that exercise co-design
 - ☐ IO, AMR, analysis

Maintain a well documented repository of kernels, reduced and compact apps

- Available to vendor partners, exascale projects, and other collaborators
- Regularly updated based on feedback

Examples of Vendor Interaction

- ☐ Flash an Early Science project for IBM BG/Q Mira
 - An official acceptance test
- □ Details under NDA, but one person working with IBM
- NVIDIA's HPC initiative has licensed FLASH for co-design
 - Multiphysics and multiscale
- Understand relatively easy changes they might make to CUDA GPU architecture that would allow FLASH to be more easily ported to it

- Because of regression testing, we understand representative workload
- Unit tests become reduced apps; comparison tests are compact/mini apps
- □ These can be easily adapted for vendor use (IBM already has the needed set; we are preparing one for NVIDIA)

Suitably stripped and documented code release licensed by vendors

Inter-node Challenges

Challenges

- Parallel IO
 - Analysis memory snapshot a large fraction of total system memory
- ☐ Higher degree of macro parallelism
 - Load balance
 - Meta-data handling
- Higher fidelity physics dictates greater coupling
 - Implicit/semi-implicit treatment

Co-Design Opportunities

- Different approach through data staging
 - Critical vs. non-critical data
 - ☐ Combine with *in situ* analysis
- New parallel algorithms
 - ☐ Trade-off between duplication and communication
 - Possibly more hierarchy
- Investigate different class of numerical algorithms
 - Less deterministic

Intra-Node and Resiliency Challenges

Challenges

Co-Design Opportunities

Intra-Node

- Memory intensive computations
- Increasing limits on available memory per process
- Bigger working sets

- Aggressive reuse of memory
- Distinguish between cores
- New algorithms
- Programming model

Faults

- □ Frequent failures
- Silent errors

- Stochastic algorithms
- Redundancy

Code Maintenance and Co-Design

- Code verification and regression testing ■Expect more non-determinism and async execution models to get performance and scalability Performance vs. Maintainability vs. Portability Auto-tuning, code to code translation, annotations
- obsolescence of code modules)
 - resting of new algorithms / implementation coming about because of new knowledge/insights

Co-Design Needs from Application

- Greater encapsulation
 - Minimize common data
 - Maximize code sections that are re-entrant
 - Increase isolation between layers
 - Separate code functionalities such that different optimizations are applicable to different layers
- Minimize kernel dependency on programming models

- Expose optimization and fault tolerance possibilities
 - Be clearer about dependencies
 - Identify critical sections Vs the non critical sections
 - Define more compact working sets
- Explore more inherently robust alternative algorithms
 - Stochastic Vs deterministic

Co-Design Needs from Hardware and Software

During Co-Design

- Ability to express and implement ideas from the last slide
- Framework for testing ideas and experimentation
- Ability to realistically assess impact on algorithm and model choices
- □ Ability to evaluate direct influence of architecture decisions
- Metrics for performance evaluation
 - Deterministic performance engineering parameters
- ☐ Fault notification and recovery models
- Tuning parameters

Co-Design Needs from Hardware and Software

At Exascale

- Measurable and predictable performance
- Reliable results within quantified limits
- Retain code portability and performance
 - Standardized interfaces for common functionalities
 - Libraries and middleware
 - Auto-tuning or code to code translation
- Memory management
 - Memory bound application
- IO management
 - Large volumes of analysis data
 - □ Currently one snapshot roughly 1/10th of memory footprint
 - Analysis a judicious combination of in-situ and post processing